

## 600V N-Channel Enhancement Mode Power MOSFET

### Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
600V	$8.5\Omega@10V$	1A

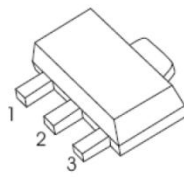
### Features

- Low gate charge
- High ruggedness
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

### Applications

- PWM Application
- Load Switch
- Power Management

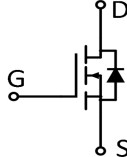
**SOT-89-3L**



1:GATE  
2:DRAIN  
3:SOURCE

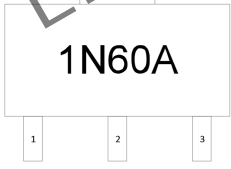
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**Schematic diagram**




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**Marking**



### Absolute Maximum rating ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Units
Drain-Source Voltage	$V_{DS}$	600	V
Gate-Source Voltage	$V_{GS}$	$\pm 30$	V
Drain Current	$I_D$	1	A
Drain Current - Pulsed <sup>1</sup>	$I_{DM}$	4	A
Single Pulsed Avalanche Energy <sup>2</sup>	$E_{AS}$	22	mJ
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	15.6	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

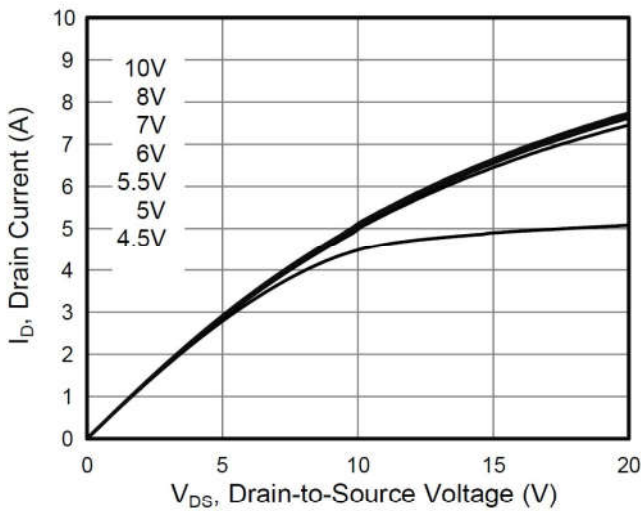
**Electrical Characteristics (T<sub>A</sub> = 25°C unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain - Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	600			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 600V, V <sub>GS</sub> = 0V			1	μA
Gate - Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±30V, V <sub>DS</sub> = 0V			±0.1	μA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	2	3	4	V
Drain-source On-resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> = 0.5A		8.5	10	Ω
<b>Dynamic Characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1.0 MHz		151		pF
Output Capacitance	C <sub>oss</sub>			13		
Reverse Transfer Capacitance	C <sub>rss</sub>			0.8		
<b>Switching Characteristics</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = 480 V, I <sub>D</sub> = 1A, V <sub>GS</sub> = 10 V		18		nC
Gate-source Charge	Q <sub>gs</sub>			1.8		
Gate-drain Charge	Q <sub>gd</sub>			1.5		
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DS</sub> = 300 V, V <sub>GS</sub> = 10V, I <sub>D</sub> = 1 A, R <sub>θ</sub> = 25 Ω		2.6		ns
Turn-on Rise Time	t <sub>r</sub>			3.3		
Turn-off Delay Time	t <sub>d(off)</sub>			9.3		
Turn-off Fall Time	t <sub>f</sub>			4.35		
<b>Source - Drain Diode Characteristics</b>						
Drain to Source Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>SD</sub> = 1A, T <sub>J</sub> = 25°C			1.2	V
Reverse Recovery Time	t <sub>rr</sub>	V <sub>DS</sub> = 400 V, V <sub>GS</sub> = 0 V, I <sub>S</sub> = 2A,		45		ns
Reverse Recovery Charge	Q <sub>rr</sub>	dI <sub>F</sub> / dt = 100 A/us		0.63		uC

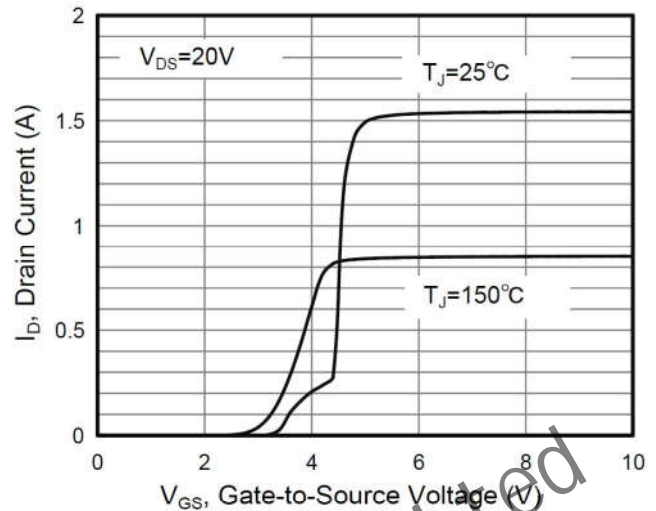
**Notes:**

- Drain current limited by maximum junction temperature.
- E<sub>AS</sub> condition: T<sub>J</sub> = 25°C, V<sub>DD</sub> = 50V, V<sub>G</sub> = 10V, R<sub>G</sub> = 25Ω, L = 10mH

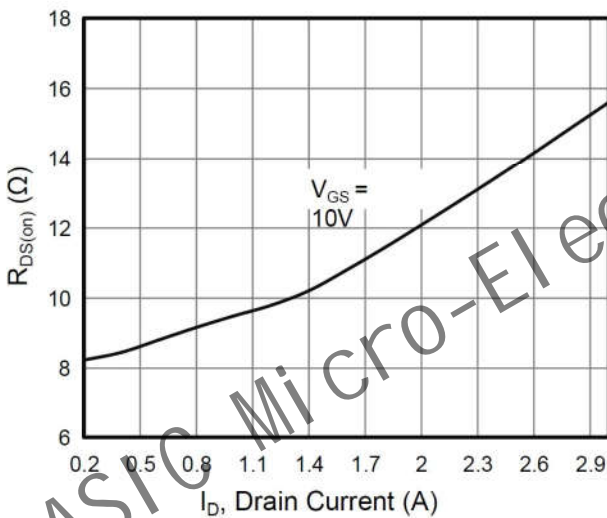
## Typical Characteristic



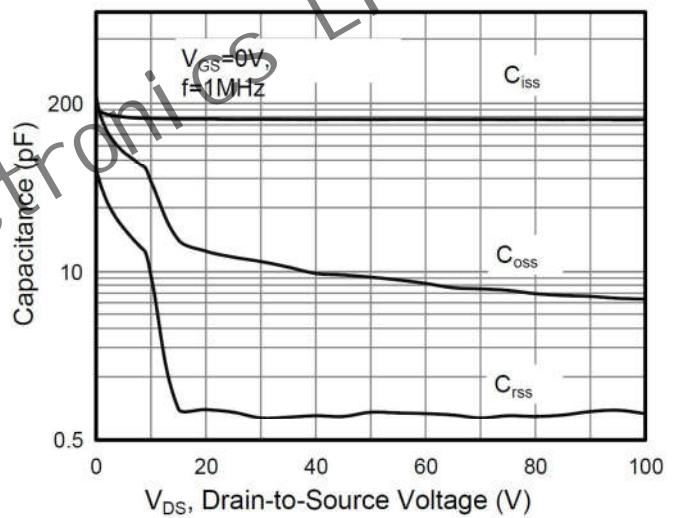
Output Characteristics



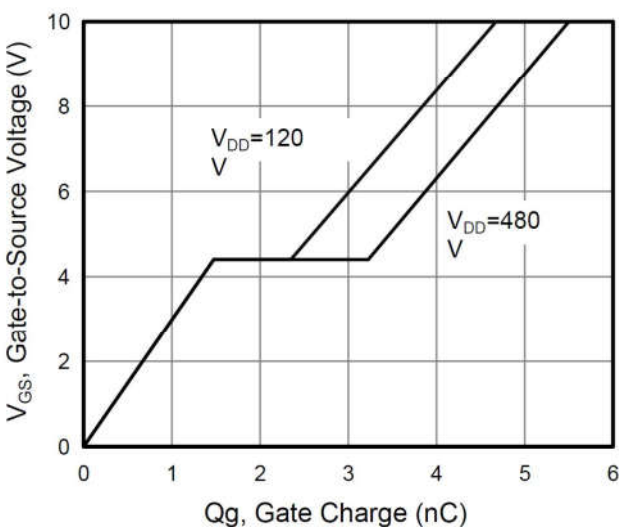
Transfer Characteristics



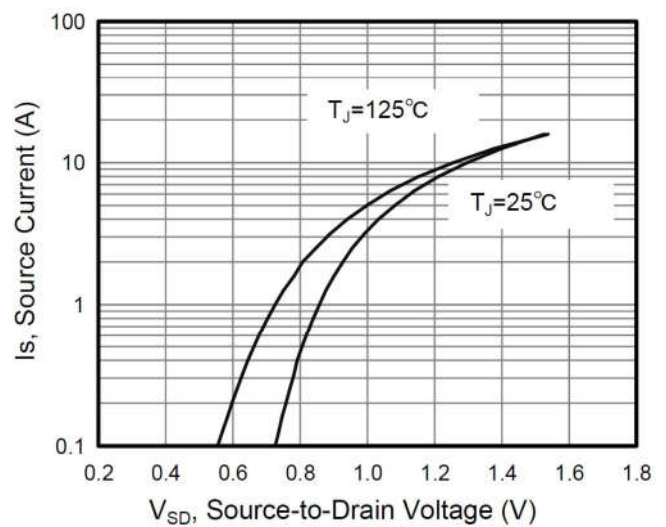
On Resistance vs. Drain Current



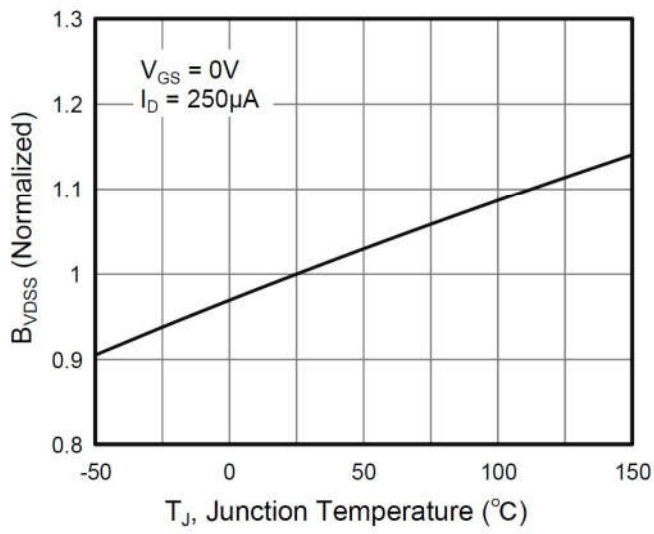
Capacitance Characteristics



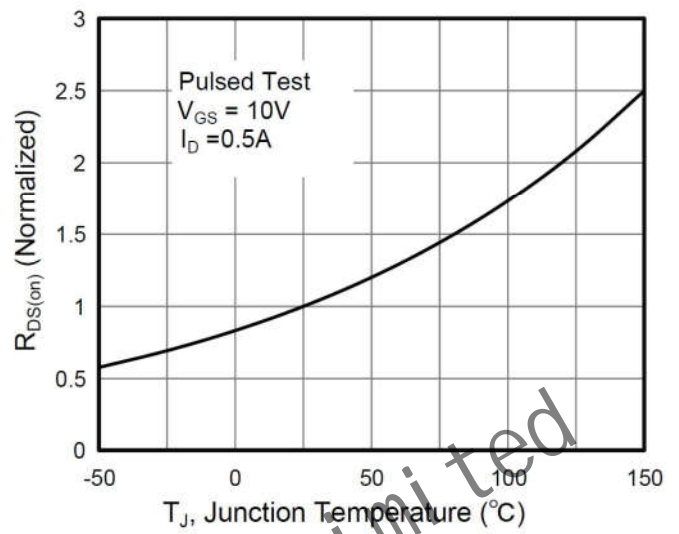
Gate Charge



Body-Diode Characteristics



**Breakdown Voltage vs Junction Temperature**

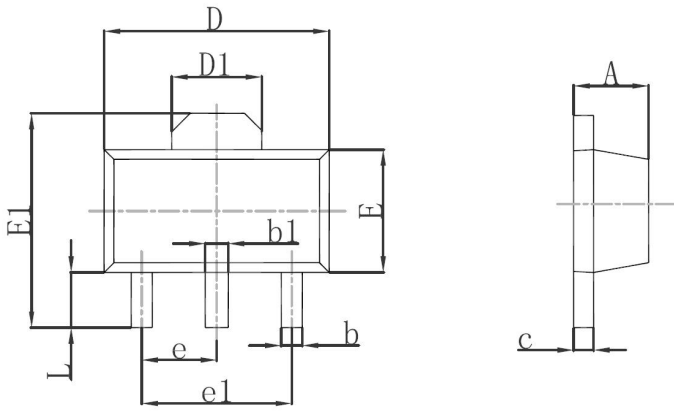


**On-Resistance vs Temperature**

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## Dimension

### SOT-89-3L



Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	1.400	1.600	0.055	0.063
b	0.320	0.520	0.013	0.020
b1	0.400	0.580	0.016	0.023
c	0.350	0.440	0.014	0.017
D	4.400	4.600	0.173	0.181
D1	1.550 REF.		0.061 REF.	
E	2.300	2.600	0.091	0.102
E1	3.940	4.250	0.155	0.167
e	1.500 TYP.		0.060 TYP.	
e1	3.000 TYP.		0.118 TYP.	
L	0.900	1.200	0.035	0.047

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